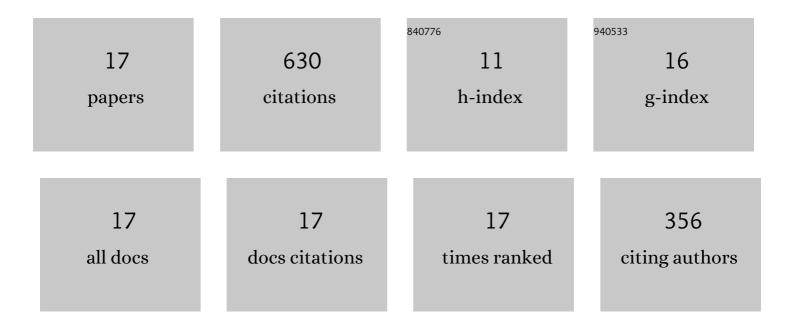
Chia-Yu Hsu

List of Publications by Year in descending order

Source: https://exaly.com/author-pdf/3803167/publications.pdf Version: 2024-02-01



Снил-Ун Нен

#	Article	IF	CITATIONS
1	Ensemble convolutional neural networks with weighted majority for wafer bin map pattern classification. Journal of Intelligent Manufacturing, 2022, 33, 831-844.	7.3	29
2	Data Visualization of Anomaly Detection in Semiconductor Processing Tools. IEEE Transactions on Semiconductor Manufacturing, 2022, 35, 186-197.	1.7	6
3	Key Feature Identification for Monitoring Wafer-to-Wafer Variation in Semiconductor Manufacturing. IEEE Transactions on Automation Science and Engineering, 2022, 19, 1530-1541.	5.2	6
4	A New Double Exponentially Weighted Moving Average Run-to-Run Control Using a Disturbance-Accumulating Strategy for Mixed-Product Mode. IEEE Transactions on Automation Science and Engineering, 2021, 18, 1846-1860.	5.2	17
5	Multiple time-series convolutional neural network for fault detection and diagnosis and empirical study in semiconductor manufacturing. Journal of Intelligent Manufacturing, 2021, 32, 823-836.	7.3	78
6	A two-phase non-dominated sorting particle swarm optimization for chip feature design to improve wafer exposure effectiveness. Computers and Industrial Engineering, 2020, 147, 106669.	6.3	3
7	A Review on Fault Detection and Process Diagnostics in Industrial Processes. Processes, 2020, 8, 1123.	2.8	112
8	An Autoencoder Gated Recurrent Unit for Remaining Useful Life Prediction. Processes, 2020, 8, 1155.	2.8	31
9	Defective wafer detection using a denoising autoencoder for semiconductor manufacturing processes. Advanced Engineering Informatics, 2020, 46, 101166.	8.0	34
10	L-measure evaluation metric for fake information detection models with binary class imbalance. Enterprise Information Systems, 2020, , 1-20.	4.7	0
11	Data-Driven Approach for Fault Detection and Diagnostic in Semiconductor Manufacturing. IEEE Transactions on Automation Science and Engineering, 2020, 17, 1925-1936.	5.2	81
12	Similarity matching of wafer bin maps for manufacturing intelligence to empower Industry 3.5 for semiconductor manufacturing. Computers and Industrial Engineering, 2020, 142, 106358.	6.3	39
13	Clustering Ensemble for Identifying Defective Wafer Bin Map in Semiconductor Manufacturing. Mathematical Problems in Engineering, 2015, 2015, 1-11.	1.1	13
14	Integrated data envelopment analysis and neural network model for forecasting performance of wafer fabrication operations. Journal of Intelligent Manufacturing, 2014, 25, 945-960.	7.3	6
15	Data Mining for Optimizing IC Feature Designs to Enhance Overall Wafer Effectiveness. IEEE Transactions on Semiconductor Manufacturing, 2014, 27, 71-82.	1.7	31
16	Overall Wafer Effectiveness (OWE): A novel industry standard for semiconductor ecosystem as a whole. Computers and Industrial Engineering, 2013, 65, 117-127.	6.3	39
17	Semiconductor fault detection and classification for yield enhancement and manufacturing intelligence. Flexible Services and Manufacturing Journal, 2013, 25, 367-388.	3.4	105